



Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:		
Product specification	SIM CARD CONN.	PS-0068		
		Page	1 OF 8	Rev. A

***** 目 錄 Content *****		
項 目 Item	內 容 Description	頁 次 Page
-----	-----	-----
1.	文件目录 Content	1
2.	变更履历 Revised history	2
3.	概述 Scope	3
4.	参考文件 Referenced Documents	3
5.	规格要求 Requirement	3~8

	核准 App.	审核 Chk.	制作 Pre.	Issued By:
By	BILL	ANDREW	BELLY	
Date	2012-10-12	2012-10-12	2012-10-12	



Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:			
Product specification	SIM CARD CONN.	PS-0068			
		Page	3 OF 8	Rev.	A

1. 概述 **Scope:**

1.1 说明 **Content**

此份产品规格书是针对由昆山嘉华电子有限公司设计和制造的 **SIM CARD CONN.** 产品所定义的产品性能和测试方法。

This product specification defines the product performance and the test methods to ensure the performance of the **SIM CARD CONN.**, which is designed and manufactured by Kunshan Jiahua Electronics Co., Ltd.

1.2 限制 **Qualification**

所有的测试和检验必须依照本文件中所要求的规格、方法进行。一旦产品的重要制程发生变更，必须立即进行品质验证和测试。

Tests and inspection shall be performed in accordance with the requirements, tests and methods contained herein. A re-qualification test shall be conducted immediately following all major process changes.

2. 参考文件 **Referenced Documents:**

EIA-364
MIL-STD-202F
MIL-P-81728A
MIL-T-10727B
JIS C 0040
JIS C 0041

若某些项目被发现本规格书中的内容与以上参考文件要求不一致时，一律依本规格书中的内容为测试依据。

In case of any contradiction between this document and referenced documents, this document will take precedence.



Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:			
Product specification	SIM CARD CONN.	PS-0068			
		Page	4 OF 8	Rev.	A

3. 规格要求 Requirements:

3.1 应用条件 Application Condition:

3.1.1 使用环境 Operating Environment:

温度: -40°C to +85°C,相对湿度:25%~85%,此条件下功能不可失效。

Temperature:-40°C to +85°C, Relative Humidity:25%~85%, Without loss of function.

3.1.2 储存环境 Storage Environment:

温度: -40°C to +100°C,相对湿度:95%或更低,此条件下功能不可失效。

Temperature:-40°C to +100°C, Relative Humidity: 95% or Less, Without loss of function.

3.2 绿色环保要求 Health, Safety and Environment

此产品中所有涉及环保有关的有害物质管控标准请参考嘉华系统文件:[JH-GP-213](#)

Hazardous substances (Environment related to be controlled substances) contained in this product should comply with the regulations specified by FAF's [JH-GP-213](#).

3.3 测试说明 Test Description

此产品性能须满足本文件 3.4 节中的各项规格要求。除非有特别申明，所有的测试和量测必须在以下条件中进行：

The product is designed to meet the requirements specified in section 3.4. Unless otherwise specified, all tests and measurements are to be performed under the following conditions:

温度 Temperature:15°C to 35°C

相对湿度 Relative Humidity: 20% to 70%

大气压 Atmospheric Pressure: 650 to 800 millimeters (25.6 to 31.5 inches) of Mercury.



文件名称 System Name:	产品品名 Description:	文件编号 Document No.:			
Product specification	SIM CARD CONN.	PS-0068			
		Page	5 OF 8	Rev.	A

3.4 测试规范和方法 Test Requirements and Methods

Table I: 性能要求 Performance Requirements

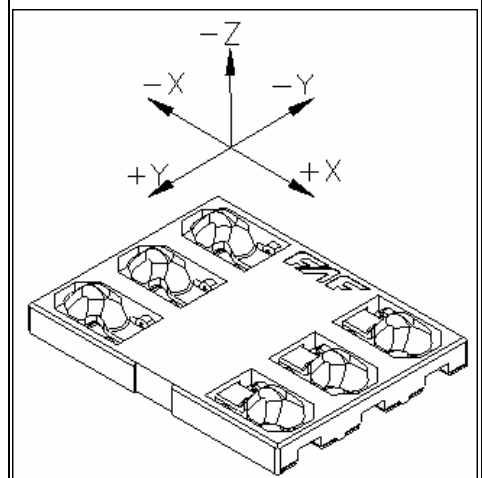
项目 Items	规格要求 Requirements	测试方法 Test Methods
3.4.1 产品外观 Visual Examination	所有零件必须组装完好,不能出现毛边,变形,刮伤,以及任何外观破坏等异常; All components shall be properly assembled and free of burrs, warps, scratches, broken chips, and other abnormalities	参考测试标准: EIA 364-18 依照相应的文件和规格书进行外观,功能,及尺寸的检验量测. Comply with method EIA 364-18 Visual, functional, and dimensional inspection complies with applicable specification and document.
3.4.2 SMT 产品耐 Reflow 高温 Withstand Temperature For SMT type	无损伤及端子掉落不良 No loose contacts or deformation.	 The graph shows a reflow temperature profile. The y-axis is temperature in degrees Celsius (°C) ranging from 0 to 250. The x-axis is time in seconds (s). The profile starts at 0°C, rises to 150°C in 30s (labeled 30s Min), then continues to rise to a peak of 250°C (labeled 250±5°C). The time spent at the peak is 20~40s. The temperature then falls back to 150°C (labeled 150~200°C) and finally to 0°C. A note indicates 'heat up 230°C Min'.
3.4.3 低功率接触阻抗 Low Level Contact Resistance	初始接触阻抗: 40 mΩ Max; 测试后接触阻抗: 50 mΩ Max; Initial: 40mΩ Max; After test: 50 mΩ Max	参考测试标准: EIA-364-23 必须保证量测结果为产品以及与之对应配对产品的焊接部位之间的阻抗值; Comply with method EIA-364-23, with the exception of the resistance readings, which shall be measured between the termination points of tested plug and connector
3.4.4 绝缘阻抗 Insulation Resistance	初始绝缘阻抗: 1000 MΩ Min. 测试后绝缘阻抗: 100 MΩ Min. Initial: 1000MΩ Min. After Test: 100 MΩ Min.	参考测试标准: EIA-364-21. 在相邻两支端子之间加载 500V 直流电压并保持 1 分钟, 然后进行测试. Comply with method EIA-364-21. Insulation resistance is measured between adjacent contacts after applying 500V DC for 2 minutes.
3.4.5 耐电压 Dielectric Withstanding Voltage	加电压期间漏电流不超过 0.5mA. 同时不能产生电弧以及而产生的短路和破坏产品的绝缘性能. No evidence of breakdown or flash burn. No burn caused by short circuit. No insulation destruction. Current leakage: 0.50 mA Max.	参考测试标准: EIA-364-20,方法 B; 在产品以及与之配对的 plug 之间加 500V 交流电压保持 1 分钟,监控漏电流. Comply with method EIA-364-20, Test Method B. apply 500 VAC 1 minute at sea level on tested plug and connectors.



Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:			
Product specification	SIM CARD CONN.	PS-0068			
		Page	6 OF 8	Rev.	A

项目 Items	规格要求 Requirements	测试方法 Test Methods
3.4.6 振动 Vibration	不产生超过 1 微秒的瞬断, 产品没有物理破坏以及零件脱落,端子接触阻抗满足规格要求. No electrical discontinuity longer than 1 u sec. No mechanical damage or looseness. Contact resistance specifications remain satisfied.	参考测试标准: EIA-364-28, 频率: 10-55~10HZ 振幅: 1.50mm, X,Y,Z 三个方向, 每个方向 2H Comply with method EIA-364-28E. Frequency: 10-55~10HZ, Amplitude: 1.50mm. along X, Y, and Z axis.(2H per axis);
3.4.7 机械冲击 Physical Shock	不产生超过 1 微秒的瞬断, 产品没有物理破坏以及零件脱落,端子接触阻抗满足规格要求. No electrical discontinuity longer than 1 u sec. No mechanical damage or looseness.Contact resistance specifications remain satisfied.	参考测试标准: EIA-364-27. 波形:半正弦波; 加速度: 50G, 时间: 11 毫秒; 沿 X,Y,X 三个方向进行, 每个方向完成正反 3 次冲击(总计 18 次冲击) Comply with method EIA-364-27, Shock Waveform: Half sine-wave, Duration Pulse : 11 msec., Acceleration: 50G, Total impacts delivered along 3 mutually each X. Y. and Z axes.(Total:18 impacts)
3.4.8 耐久插拔 Durability	完成 5000 次插拔以后, 必须满足相应机械及电气规格. Mating and Unmating 5000 cycles Meet related mechanical and electrical specification.	参考测试标准: EIA-364-09; 公母互配的产品进行插拔测试,每小时不超过 500 次; 测试如图 5 个方向 Comply with method EIA 364-09 Mated and unmated each connector at Max rate of 500 cycles per hour.





Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:			
Product specification	SIM CARD CONN.	PS-0068			
		Page	7 OF 8	Rev.	A

项目 Items	规格要求 Requirements	测试方法 Test Methods
3.4.9 端子正向力 Normal force	最小每 PIN 50gf 50gf or more per pin	参考测试标准: EIA-364-13. 用 SIM CARD 以每分 25+/-3mm 的速度下压 (如上图+Z 方向). 位移量:0.50mm When applied SIM CARD mating at speed 25+/-3mm/min Stroke: 0.50mm
3.4.10 温度冲击 Thermal shock	测试后满足相应机械及电气规格; Meet related mechanical and electrical specification.	参考测试标准: EIA-364-32; -40°C 和 +70°C 各 30 分钟, 过渡时间: 最大 5 分钟, 总计 10 个循环. Comply with method EIA-364-32. -40°C for 30 minutes and +70°C for 30 minutes for 10 cycles. Transition time:5 min. max.
3.4.11 盐雾实验 Salt Spray	测试后产品须满足 3.4.3, 3.4.4 以及 3.4.5 规格要求. After the test, the sample shall pass the test specified in 3.4.3, 3.4.4, 3.4.5	参考测试标准: EIA-364-26 盐水温度: 35±2°C, 浓度 5±1%, 时间: 48 小时. Comply with method EIA-364-26. Salt solution temperature 35±2°C, Concentration 5±1%, Duration: 48H
3.4.12 耐湿度 Humidity Verification	测试后产品须满足 3.4.3, 以及 3.4.5 规格要求. Meet 3.4.3, 3.4.5 specification	参考测试标准: EIA-364-31 中方法 II, 条件 A; 产品互配在以下条件中放置 96 小时: 温度: 60°C 相对湿度: 90~95% Comply with method II. Test condition A of EIA-364-31. Subject mated connectors to 96 hours at 60°C with 90~95% relative humidity.
3.4.13 温度寿命 Temperature life	测试后产品须满足 3.4.3, 以及 3.4.8 规格要求. Meet 3.4.3, 3.4.8 specification	参考测试标准: EIA-364-17 产品互配后放置在 70°C 条件下总计 96 小时. Comply with EIA-364-17. Subject mated connectors to temperature life at 70°C for 96 hours.



Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:			
Product specification	SIM CARD CONN.	PS-0068			
		Page	8 OF 8	Rev.	A

3.5 Test Sequence

Test, Measurement or Examination	A		B		C		D		E		F	
	Sample size	5	Sample size	5	Sample size	5	Sample size	5	Sample size	5	Sample size	5
1. Visual examination	1, 3, 9		1, 3, 10		1, 3, 9		1, 3, 11		1, 3, 11		1, 3, 11	
2. Withstand Temperature For SMT type	2		2		2		2		2		2	
3. Normal force	4, 7		4, 8		4, 7							
4. Low Level Contact Resistance	5, 8		5, 9		5, 8		4, 8		4, 8		4, 8	
5. Dielectric Withstanding Voltage							5, 9		5, 9		5, 9	
6. Insulation Resistance							6, 10		6, 10		6, 10	
7. Durability	6											
8. Vibration			6									
9. Physical shock			7									
10. Thermal shock					6							
11. Salt Spray							7					
12. Humidity									7			
13. Temperature life											7	